Laboratory Data Sheet

De-soldering Wick

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No-Clean Desoldering Wick

PRODUCT DESCRIPTION

LOCTITE® Product Multicore™ De-soldering Wick is designed for static-free desoldering and repair of PC boards without the need for subsequent cleaning.

We use a special halide-free vacuumised no-clean, flux-coated copper braid designed to improve wicking. It will not lose its efficiency even after prolonged storage in humid conditions. The wick remains flexible and will not flake. PCBs meet MIL-P-28809A Cleanliness Test without cleaning.

- Faster and increased solder absorption
- Negligible residues which are non-corrosive, clear and non-hydroscopic
- Heat stable coating
- Contains small amount of halide-free synthetic resin flux that does not need to be removed.

Directions for Use

Lay de-soldering wick over the solder requiring removal and place the soldering iron tip on top of the copper braid. The braid and solder beneath will gradual heat until the solder melts and is absorbed into the braid by capillary action. Remove the braid, cut off the solder-filled length and dispose properly.

Packaging:

Multicore™ De-soldering Wick is supplied in static dissipative plastic spools of 1.5m (5ft) or 3m (10ft) spools.

Packaged ten spools per sleeve and five sleeves per box.

Also available in 100ft econo-spools.

DESOLDERING WICKS	
Size Reference	**Approximate Width**
NC-OO	0.8mm (0.03in)
NC-AA	1.5mm (0.06in)
NC-AB	2.2mm (0.08in)
NC-BB	2.7mm (0.1in)

Data Ranges

The data contained herein may be reported as a typical value and/or range. Values are based on actual test data and are verified on a periodic basis.

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Loctite Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Loctite Corporation's products. Loctite Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Loctite Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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